

IN THE SPECIFICATION

Applicants request that the following paragraphs in the specification be amended as follows:

1) The paragraph beginning on page 7, line 20:

The package 300 of the second embodiment, shown in FIG. 6, is similar to the package of the first embodiment shown in FIG. 4B. However, the package 300 of FIG. 6 differs from that of FIG. 4B in that beam leads 52 of a tape circuit substrate 50 are formed on the top surface of a base film 51, and a protective layer 53 may be formed on the beam leads 52 and the top surface of the base film 51. Though not depicted in FIG. 6, the beam lead 52 in this embodiment has a wavy portion as well that could be configured in various shapes and dimensions as discussed above and illustrated in FIGS. 5A to 5C.